



SOT684-18

plastic, thermally enhanced very thin quad flat non-ledged package; 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.85 mm body

24 February 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-01-2020
Manufacturer package code	98ASA00589D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
seated height	0.8	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	56	-	



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2 Package outline

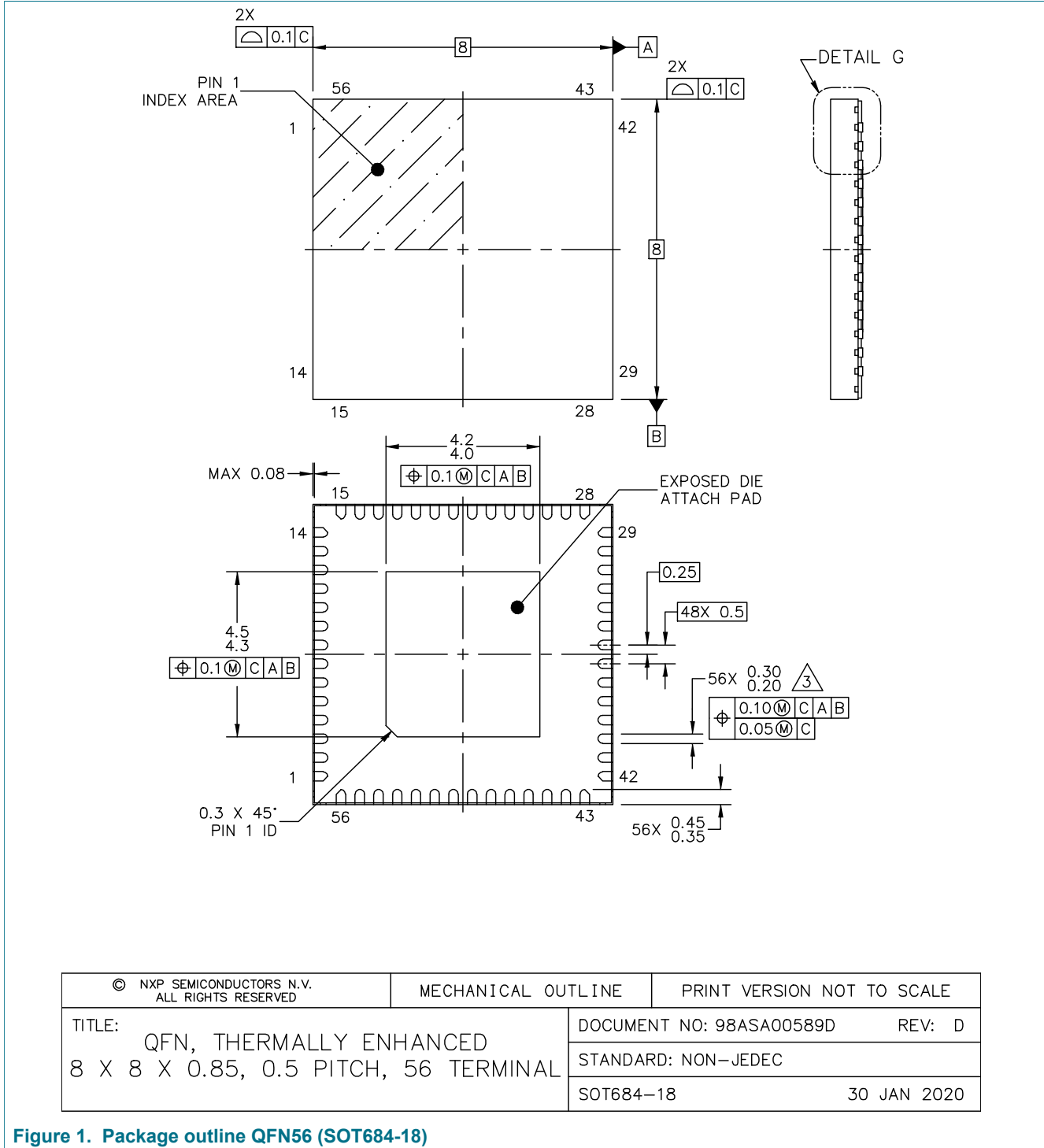


Figure 1. Package outline QFN56 (SOT684-18)

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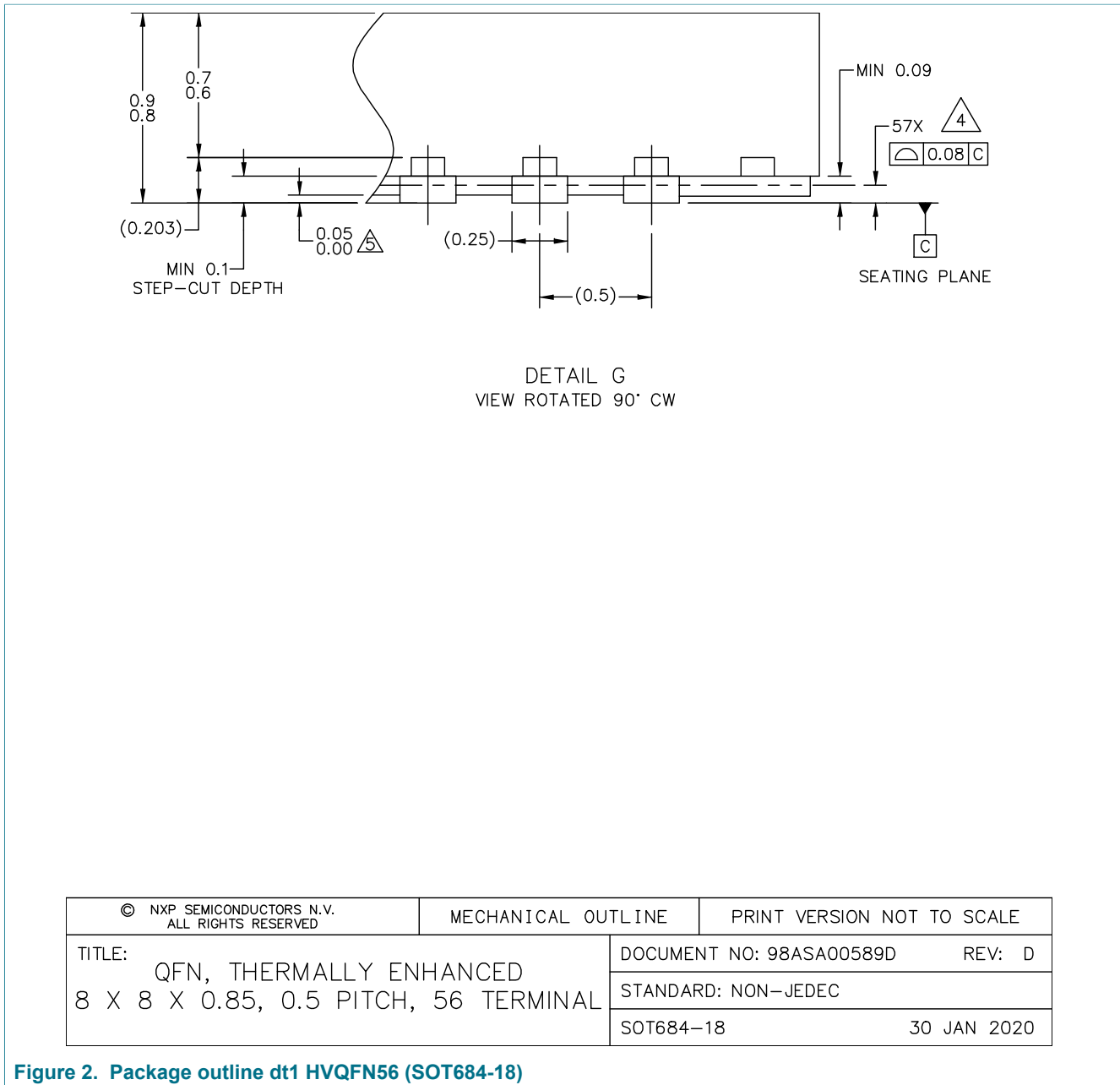


Figure 2. Package outline dt1 HVQFN56 (SOT684-18)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- ⚠ THIS DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM TERMINAL TIP.
 - ⚠ BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
 - ⚠ THIS DIMENSION APPLIES ONLY FOR TERMINALS.

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TITLE: QFN, THERMALLY ENHANCED 8 X 8 X 0.85, 0.5 PITCH, 56 TERMINAL	DOCUMENT NO: 98ASA00589D	REV: D
	STANDARD: NON-JEDEC	
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Figure 3. Package outline note HVQFN56 (SOT684-18)

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3 Legal information

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